

Material:

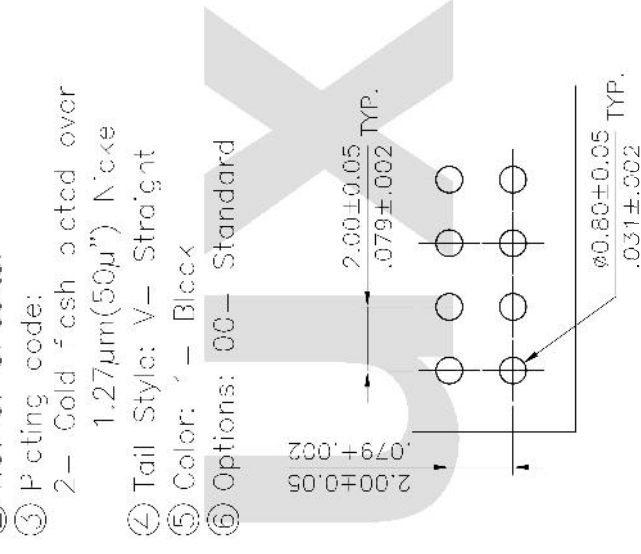
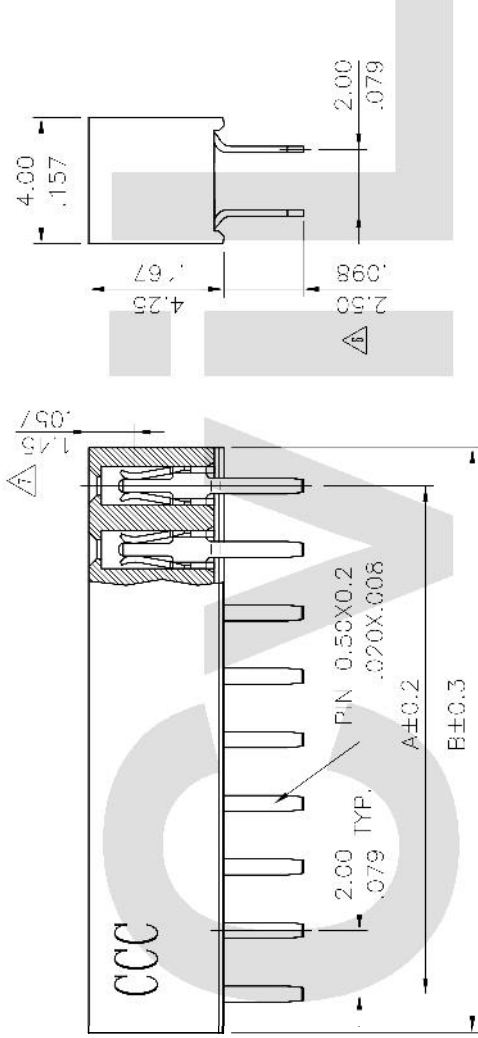
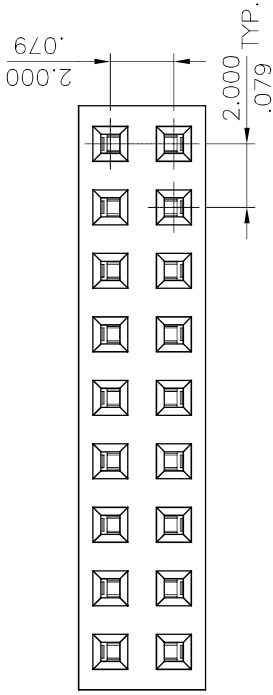
* Insulation: High Temperature Plastic UL 94V-0

* Contact: Phosphor Bronze

Ordering Code:

CB74 ** 2 V 1 00
 ① ② ③ ④ ⑤ ⑥

- ① Series No.
- ② NO. of Circuits:
- ③ Plating code:
 2 - Gold flash coated over
 1.27μm(50μ") Ni/Cr
- ④ Tail Style: V - Straight
- ⑤ Color: - Black
- ⑥ Options: 00 - Standard




A = 2.00 * No. of Spaces

B = A + 2.4

* Available in 4 through 80 circuits

Recommended P.C. Board Layout

⑥	Sun	2/05-07	ECN07055	DATE	3/14-07	UNIT: mm / inch	TITLE: 2.00MM(.079") DUAL ROW BOARD MOUNT CONNECTOR	 瀚荃股份有限公司 CviLux Corporation		<div style="border: 1px solid black; padding: 2px; display: inline-block;">RoHS Compliant</div>	
⑤	Clark	11/03-06	ECN06404	DRAWN BY: Sandy	3/15-07	TOLERANCE UNLESS OTHERWISE SPECIFIED X ± 0.30 / .012 X* ± 1" .XX ± 0.20 / .008 X ± .XXX ± 0.10 / .004 .XX ±	DRAWING NO. CB7401SI				
④	Sandy	10/05-06	ECN06346/ECR06055-1	ENGINEER: Easley	3/15-07		MATERIAL:	SCALE 4 / 1	SHEET 1 OF 1		
③	Sandy	3/14-07	ECN07006	CHECKED BY: David	3/15-07		FINISH:				
SYM	NAME	DATE	REVISIONS	APPROVED BY: Alex	3/15-07						

General Plating

TABLE- 1 (Tin-Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
1	30 μ " Tin Min.	Reflow Plated	Overall	Crimp clip terminal
	80 μ " Tin Min.	30 μ " Nickel Min.	Overall	Crimp clip terminal
	100 μ " Tin Min.	30 μ Nickel Min.	Overall	Solder tail terminal & Board in terminal
	120 μ " Tin Min.	30 μ Nickel Min.	Overall	Square or round pin
	120 μ " Tin	50 μ Nickel Min.	Overall	SMT type terminal

TABLE- 2 (Gold -Plated)

Plating Code	Top Plating Thickness	Under Plating Thickness	Area	Match Type
2	0.8 μ " Gold Min.	50 μ " Nickel Min.	Overall	Square or round pin
	1.2 μ " Gold Min.			Other type
3	15 μ " Gold Min.	50 μ " Nickel	Overall	All type
4	30 μ " Gold Min.	50 μ " Nickel	Overall	All type
5	50 μ " Gold Min.	50 μ " Nickel	Overall	All type
7	3 μ " Gold Min.	50 μ " Nickel	Overall	All type
8	80 μ " Gold Plated over	50 μ " Nickel	Overall	CP35
9	5 μ " Gold Plated over	50 μ " Nickel	Overall	All type
A	Selective 1.2 μ " Gold Flash	50 μ " Nickel	Contact Area	All type
B	Selective 15 μ " Gold	50 μ " Nickel	Contact Area	All type
C	Selective 30 μ " Gold	50 μ " Nickel	Contact Area	All type

General Plating

D	Selective 10 μ ” Gold	50 μ ” Nickel	Contact Area	All type
E	Selective 50 μ ” Gold	50 μ ” Nickel	Contact Area	All type
F	Selective 80 μ ” Gold	50 μ ” Nickel	Contact Area	CP35
G	Selective 5 μ ” Gold	50 μ ” Nickel	Contact Area	CCF
I	Selective 15 μ ” Gold	1.2 μ ” Gold Flash Plated over 50 μ ” Nickel	Contact Area	All type
J	Selective 30 μ ” Gold	1.2 μ ” Gold Flash Plated over 50 μ ” Nickel	Contact Area	All type
K	Selective 5 μ ” Gold	80 μ ” Nickel	Contact Area	All type

SOLDERABILITY:

TEST ITEM	TEST CONDITION	PROCESS	TEST REQUIREMENT
Solderability	Soldering time: 5 \pm 0.5 Second Soldering pot: 230 \pm 5 $^{\circ}$ C	Sn - Pb Process	Minimum: 95% of immersed area
	Soldering time: 3 \pm 0.5 Second Soldering pot: 245 \pm 5 $^{\circ}$ C	Lead Free Process	

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1. SCOPE:

This specification contains the test requirement of subject connectors when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:

MIL - STD - 202	Methods for test of connectors for electronic equipment
MIL - STD - 1344	Test methods for electrical connectors
J-STD-020	Resistance to soldering Temperature for through hole Mounted Devices
SS-00254	Test methods for electronic components ,LEAD-FREE soldering Part design standards

3. APPLICABLE SERIES NO.: **CB74 Series**

4. SHAPE, CONSTRUCTION AND DIMENSIONS

See attached drawings

5. MATERIALS

See attached drawings

6. ACCOMMODATED P.C.BOARD

0.8 mm (.031") ~ 1.6 mm (.063")



REVIEWED : Alex APPROVED : David VERIFIED : Jim .



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7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1 minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Contact retaining force in insulator	Retention speed 25± 3 mm per minute form housing	More than 400 gram
8.2	Single contact insertion force	Measure force to insertion using 0.46 mm square pin at speed 25± 3 mm per minute	600 gram max.
8.3	Single contact withdrawal force	Measure force to withdrawal using 0.46 mm square pin at speed 25± 3 mm per minute	20 gram min.
8.4	Durability	Connector shall be subjected to 50 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Vibration	1.5 mm 10 - 55 - 10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.2	Solderability	Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5 °C Lead-Free Process: Soldering time: 3 ± 0.5 second Soldering pot: 245 ± 5 °C	Minimum: 90% of immersed area



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	ITEM	TEST CONDITION	REQUIREMENT
9.3	Resistance to soldering heat	DIP Type Tin-Lead Process: Soldering time: 5 ± 0.5 second Soldering pot: 240 ± 5 °C DIP Type Lead-Free Process Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5 °C SMT Tin-Lead Type Process: Refer Reflow temperature profile(11.1) Soldering time: 10 second Max. Soldering pot: 230 ± 5 °C SMT Type Lead-Free Process: Soldering time: 20 second Max. Soldering pot: 250~260 °C Refer Reflow temperature profile(11.2)	No damage
9.4	Heat aging	105± 2 °C, 96 hours	No damage
9.5	Humidity	40±2 °C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3
9.6	Temperature cycling	One cycle consists of : (1) -55 ⁺⁰ ₋₃ °C , 30 min. (2)Room temp. 10-15 min. (3) 85 ⁺³ ₋₀ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.7	Salt spray	Temperature: 35± 3 °C Solution: 5± 1% Spray time: 48± 4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial



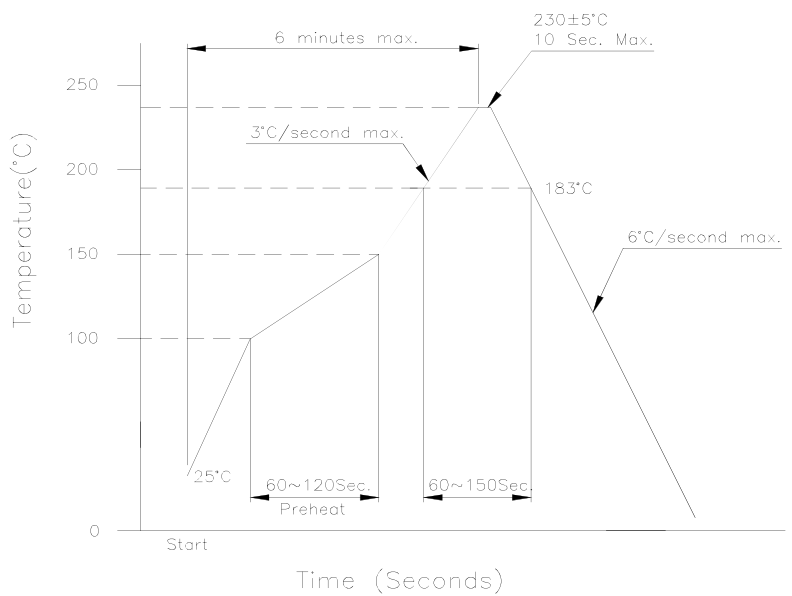
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10. AMBIENT TEMPERATURE RANGE:

-40 to + 105 °C ; + 215 °C intermittent (Vapor Phase Solder Reflow) for SMT type

11. Recommended IR Reflow Temperature Profile:

11.1 Using Typical Solder Paste



11.2 Using Lead-Free Solder Paste

